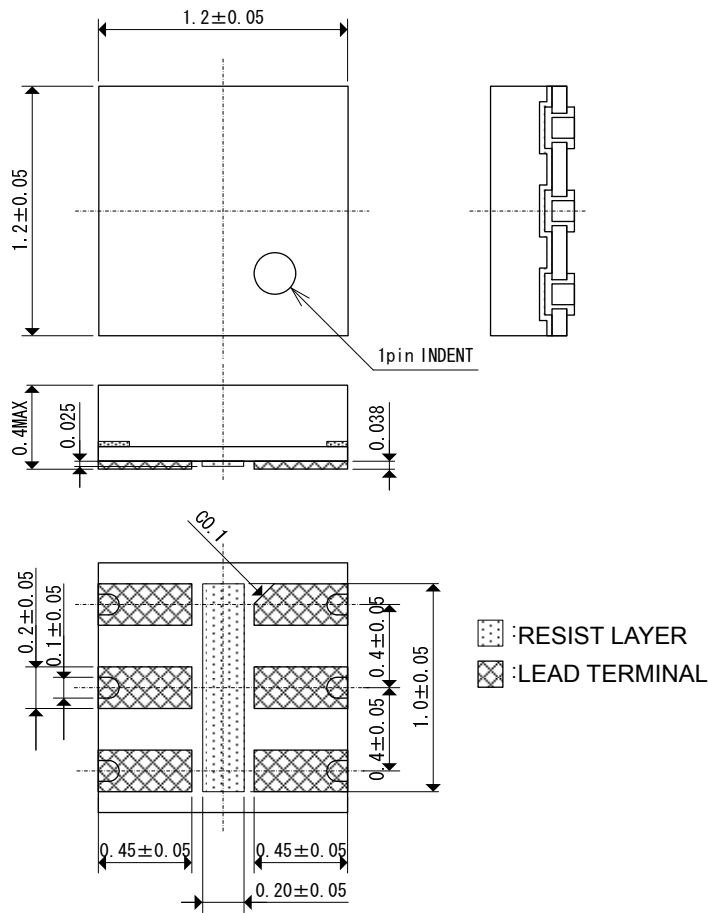


# Packaging Information / Reference Pattern Layout Dimensions

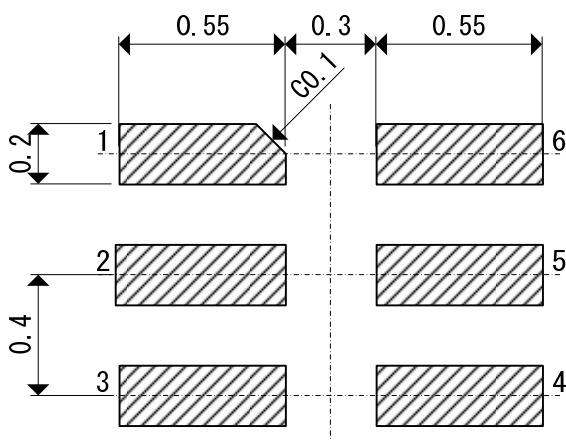
## ●LGA-6A01

### ■Packaging Information

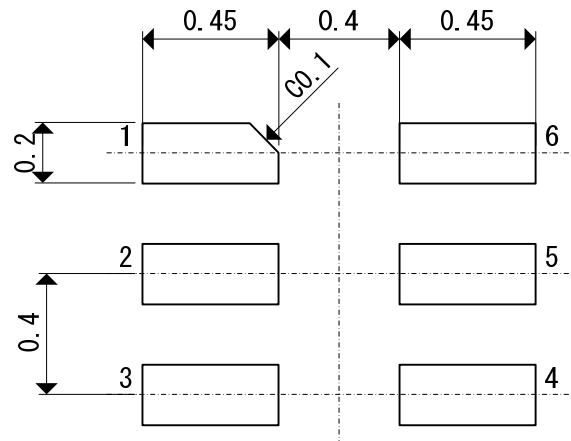
Unit: mm



### ■Reference Pattern Layout Dimension



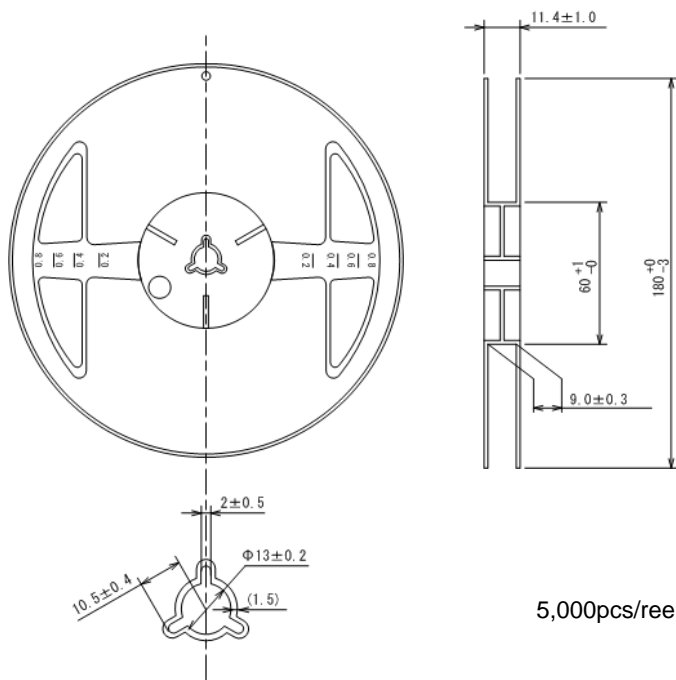
### Reference metal mask design



# Taping Specifications

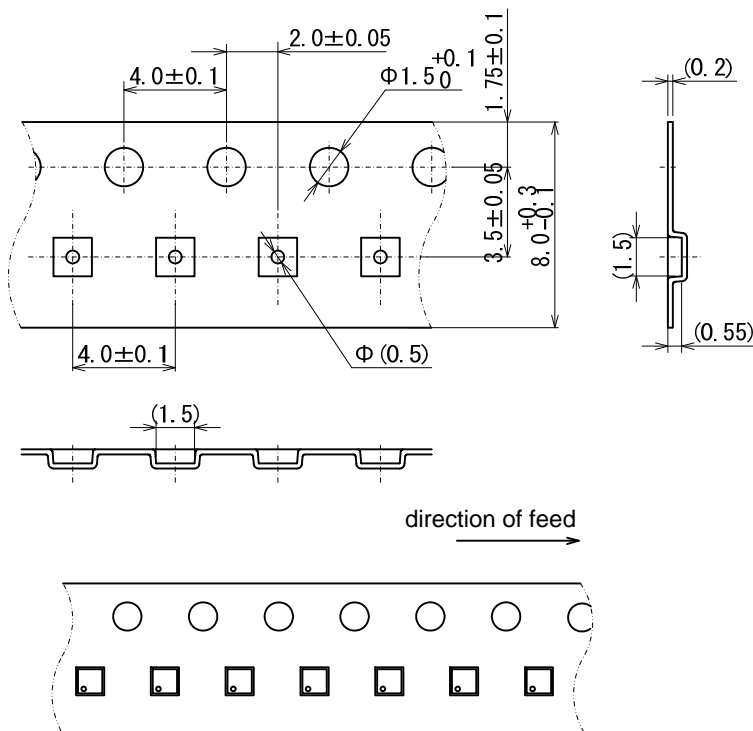
## ●LGA-6A01 Reel

Unit: mm



5,000pcs/reel

## ●Taping Specifications



R Type : [Device orientation : Right]

Standard feed

**●LGA-6A01 Power Dissipation**

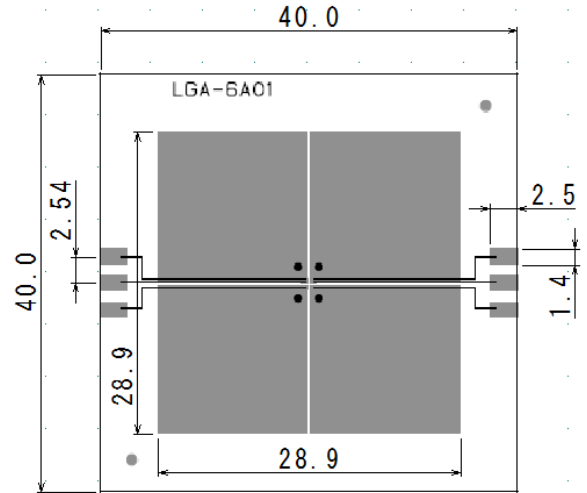
Power dissipation data for the LGA-6A01 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as the reference data taken in the following condition.

**1. Measurement Condition**

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board Dimensions: 40mm×40mm (1600mm<sup>2</sup> in one side)
- Metal Area : 1<sup>st</sup> Metal Layer about 50%  
 2<sup>nd</sup> Inner Metal Layer about 50%  
 3<sup>rd</sup> Inner Metal Layer about 50%  
 4<sup>th</sup> Metal Layer about 50%  
 Each heat sink back metal is connected to the Inner layers respectively.
- Material : Glass Epoxy (FR-4)
- Thickness : 1.0 mm
- Through-hole : 4 x 0.4 Diameter



Evaluation Board (Unit: mm)

**2. Power Dissipation vs. Ambient temperature**

Board Mount (Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	650	153.85
85	260	

